

Customer No.: 31561
Docket No.: 11182-US-PA
Application No.: 10/710,582

Patent

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Customer No.: 31561
Docket No.: 11182-US-PA
Application No.: 10/710,582

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Meng-Jen Wang
Application No. : 10/710,582
Filed : 2004/7/22
For : METHOD OF FABRICATING FLIP CHIP BALL GRID
ARRAY PACKAGE
Art Unit : 2812
Examiner : STEVENSON, ANDRE C.

TRANSMITTAL LETTER

002-1-571-273-8300

(Via fax : 1+4 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated September 14, 2005(Paper No.: 8051), please find the Response to Office Action, in 4 pages.

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 11182-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date : NOV. 10, 2005

By :

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